

2024 Japan-Taiwan Workshop on Electronic Interconnection IV



The “2024 Japan-Taiwan Workshop on Electronic Interconnection IV” is the fourth workshop on electronic interconnection co-organized between Japan and Taiwan researchers. This workshop, starting from 2017 held in National Taiwan University, Taiwan, aims at “Invent Yourself” and strengthening the friendship and cooperation between Japan and Taiwan Universities/Institutes. We sincerely invite you to participate in this workshop, which is held in conjunction with 2024 International Conference on Electronic Packaging (ICEP) in Toyama, Japan.

Time & Venue:

April 16th, 2024

Toyama International Conference Center, Toyama, Japan

Important dates:

Deadline of abstract submission: **February 16th, 2024**

Deadline of registration: **March 16th, 2024**

Registration fee (including lunch and banquet):

Faculty: 20,000 JPY (tentative)

Student: 2,000 JPY (tentative)

Organizers:

Prof. Shih-kang Lin (NCKU)

Prof. C. Robert Kao (NTU)

Prof. Jun Mizuno (NCKU)

Prof. Wen-Dung Hsu (NCKU)

Prof. Albert T. Wu (NCU)

Prof. Yee-wen Yen (NTUST)

Prof. Chih-Ming Chen (NCHU)

Prof. Yu-chen Liu (NCKU)

Prof. Eiji Higurashi (Tohoku Univ.)

Prof. Tomoyuki Hatakeyama (Toyama Pref. Univ.)

Prof. Hiroshi Nishikawa (Osaka Univ.)

Prof. Masahiro Inoue (Gunma Univ.)

Dr. Akitsu Shigetou (NIMS)

Prof. Takafumi Fukushima (Tohoku. Univ.)

Prof. Kai Takeuchi (Tohoku Univ.)

Co-sponsor: The Japan Institute of Electronics Packaging (JIEP)

Contacts: higurashi@tohoku.ac.jp (Prof. Eiji Higurashi)

kai.takeuchi@tohoku.ac.jp (Dr. Kai Takeuchi)